



Title: IMPROVEMENT IN OR
RELATING TO CIRCUIT BOARD
HAVING SOLDER BUMPS
Inventor(s): Haruhiko MURATA et al.
Appl. No.: 08/825,400

FIG.1A

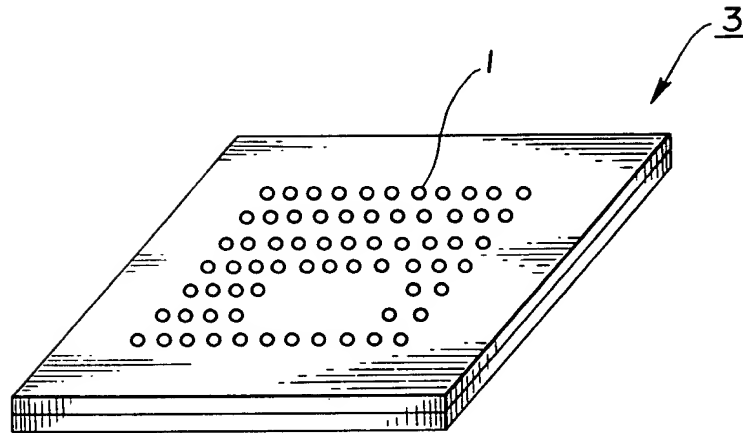


FIG.1B

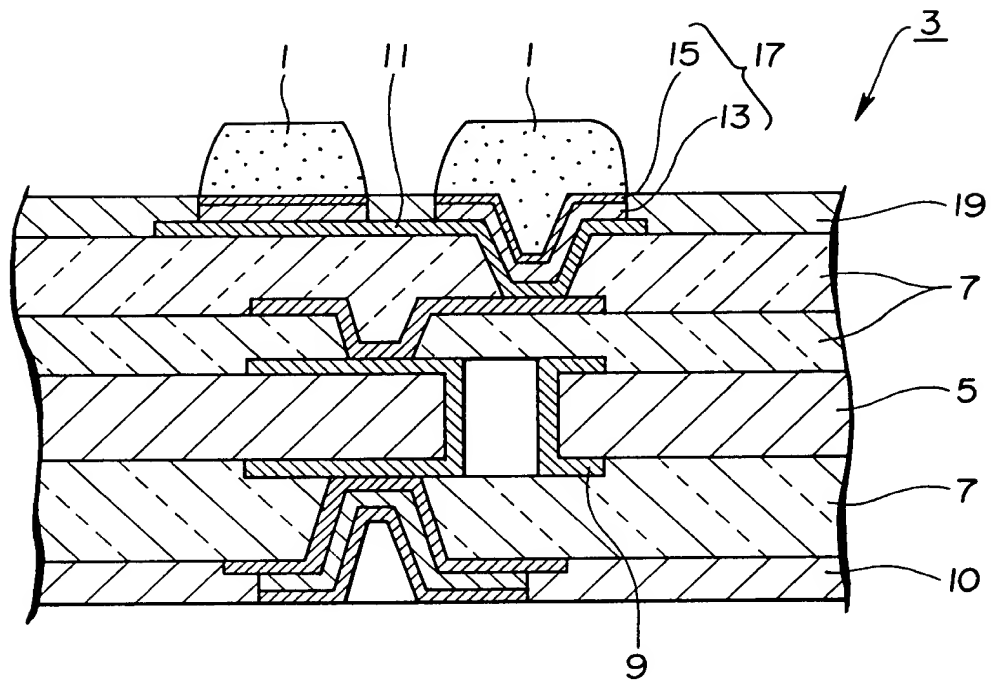




FIG.2A

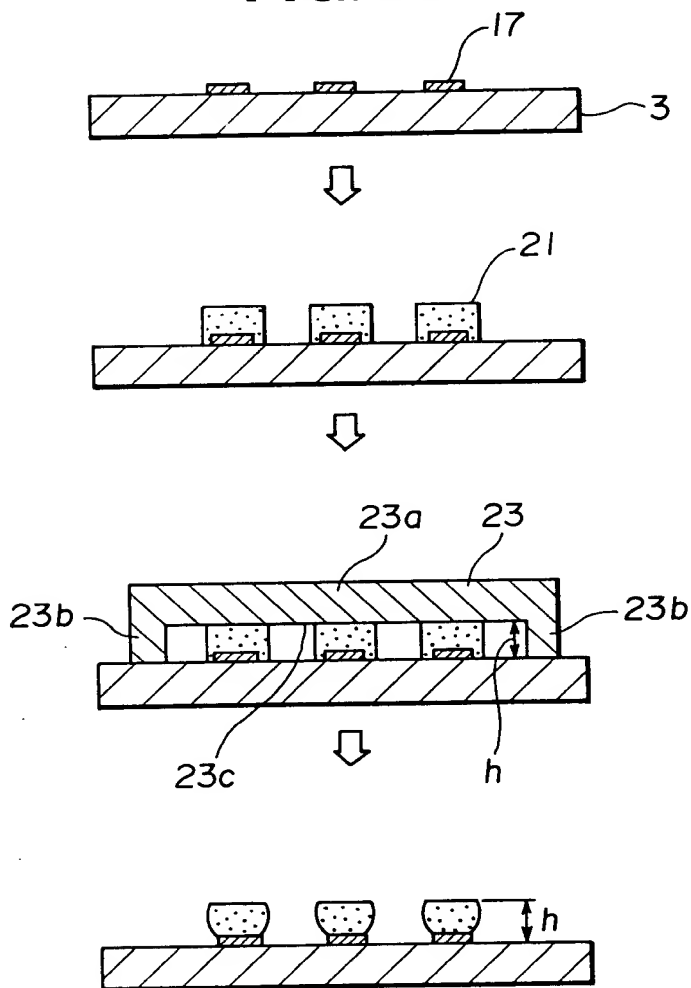
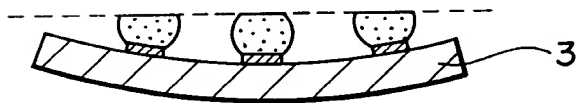


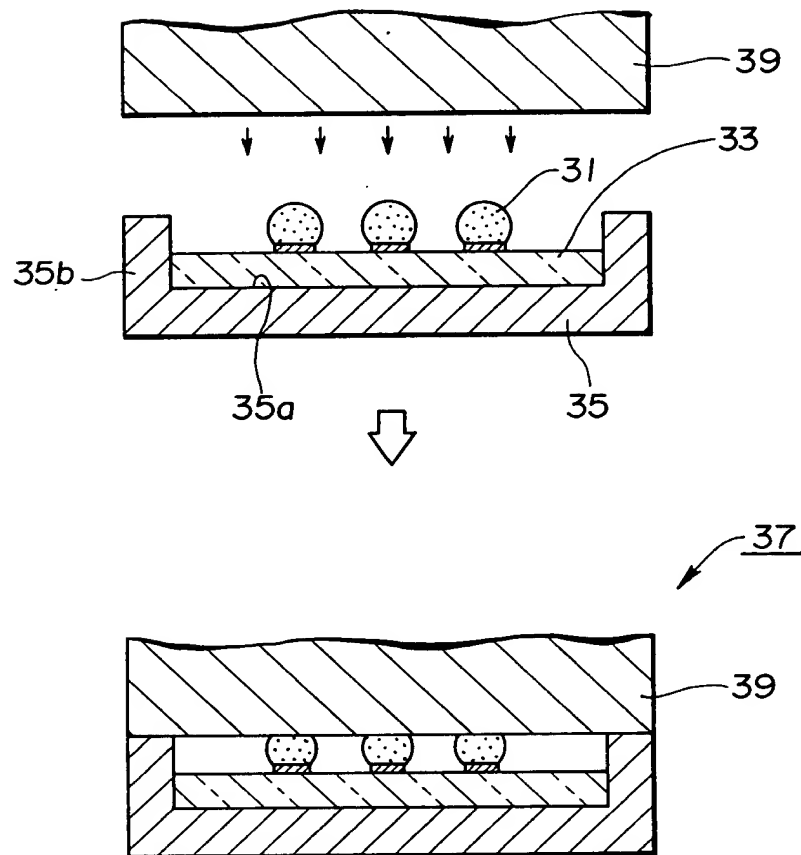
FIG.2B





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FIG.3





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FIG.4A

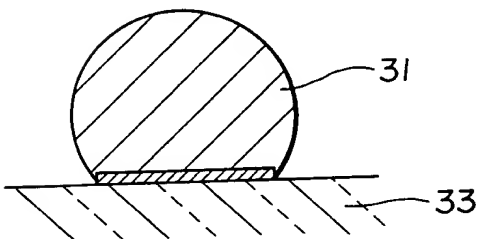


FIG.4B

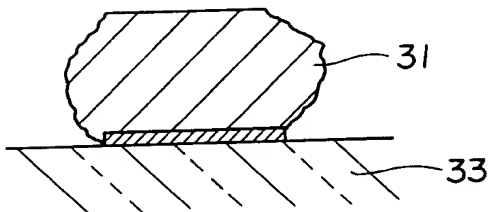
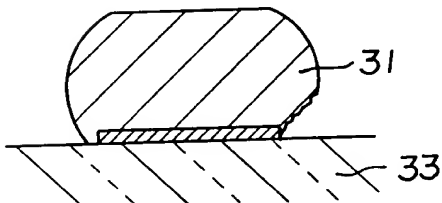


FIG.4C





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FIG.5

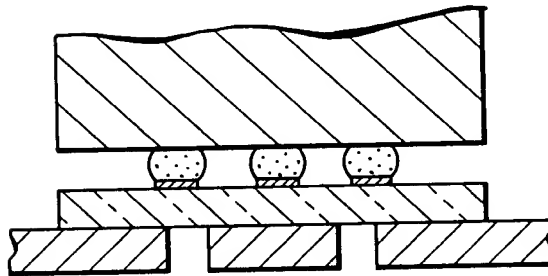
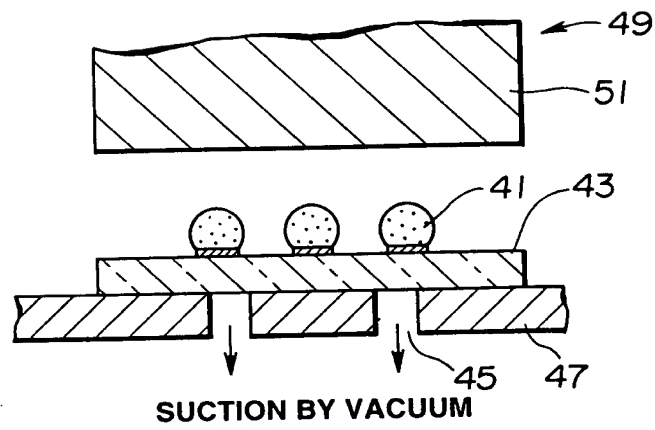




FIG.6

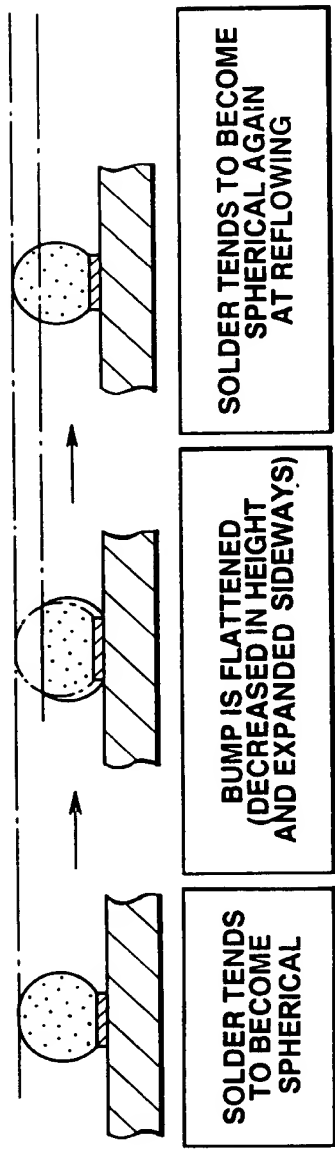
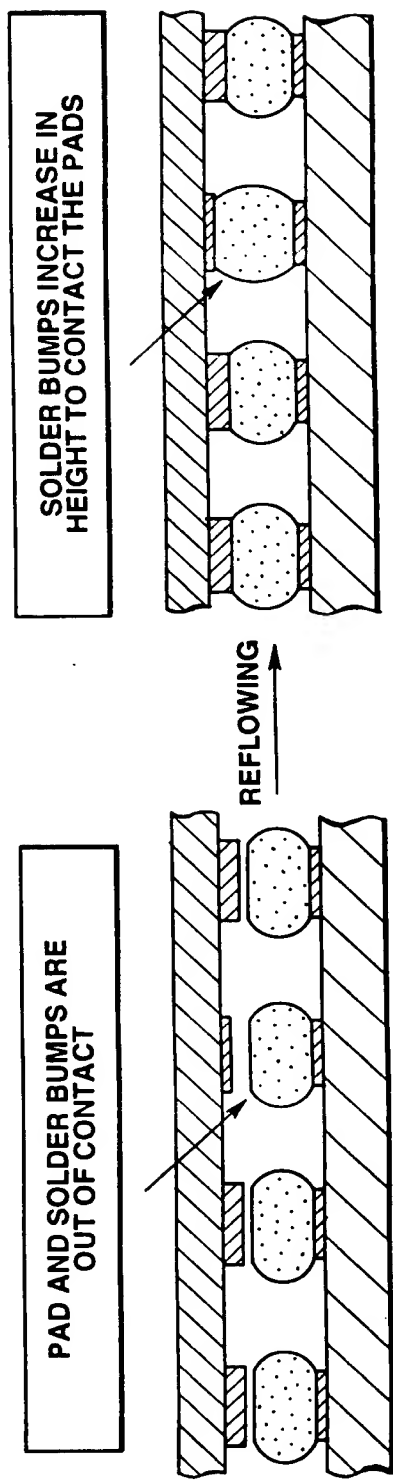


FIG.7





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FIG.8

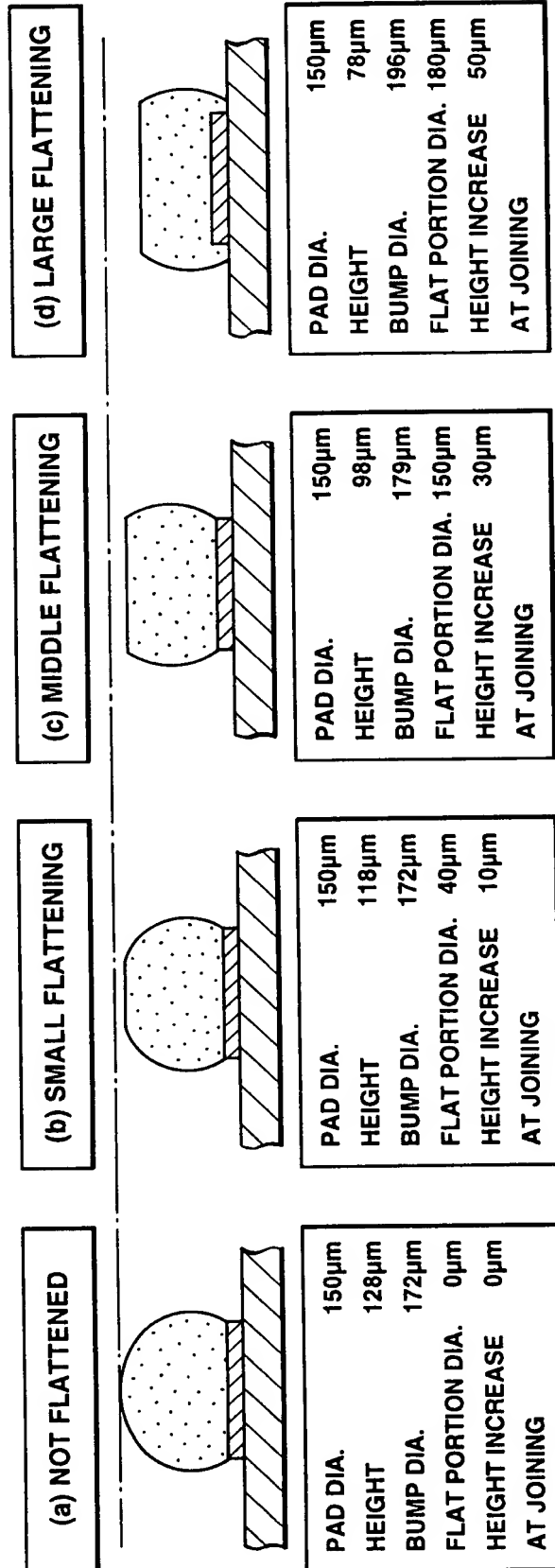




FIG.9

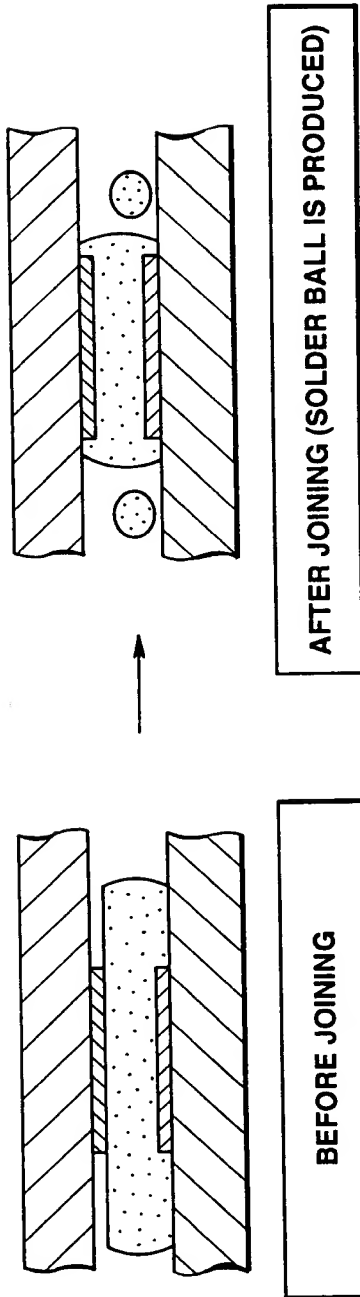


FIG.10

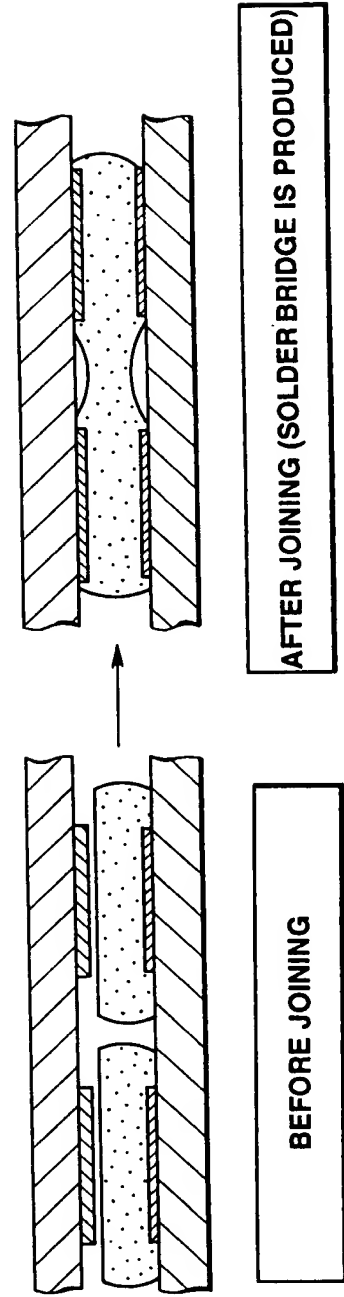




FIG.11A

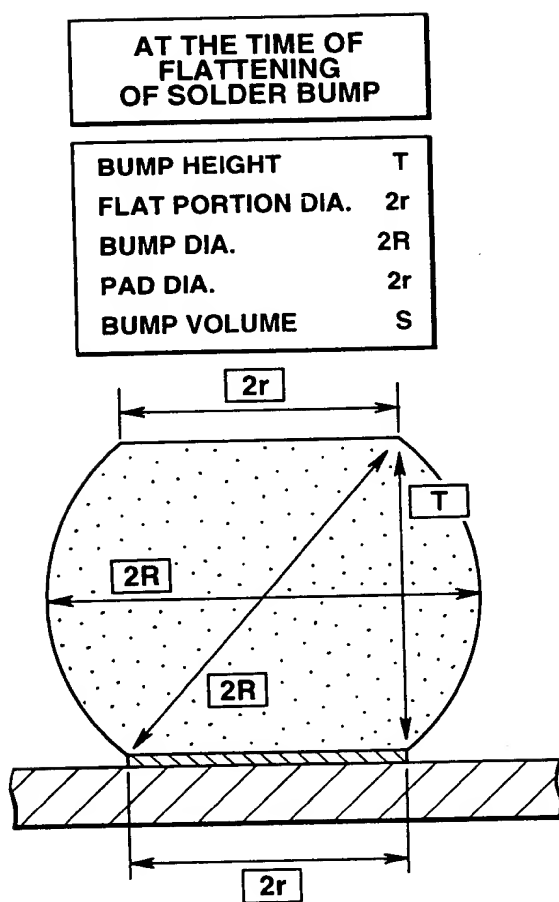
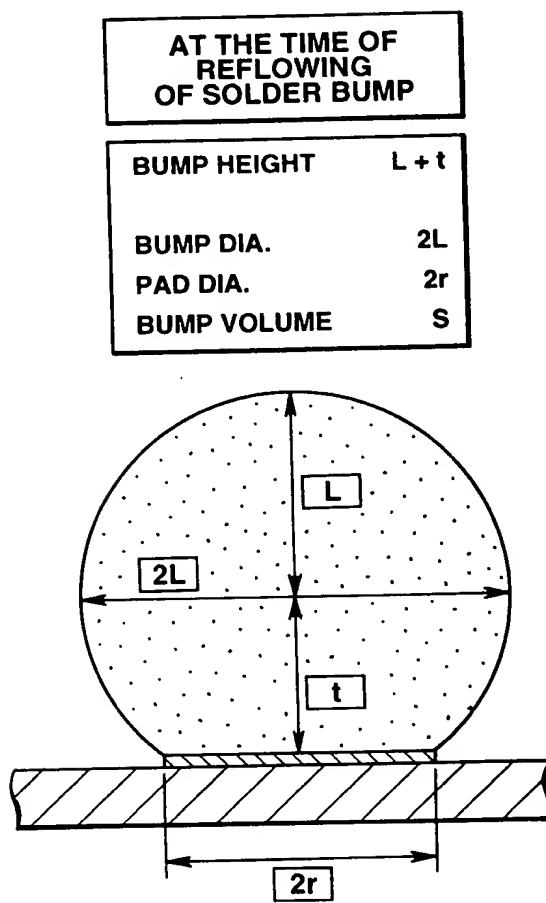


FIG.11B





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FIG.12A

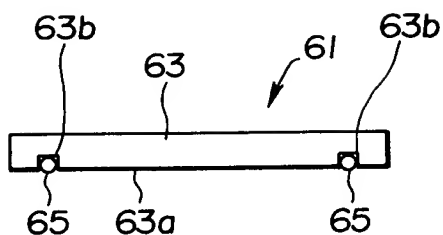


FIG.12C

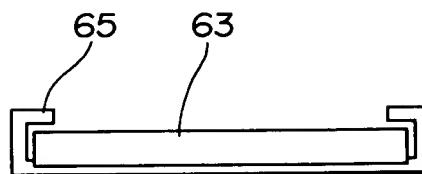
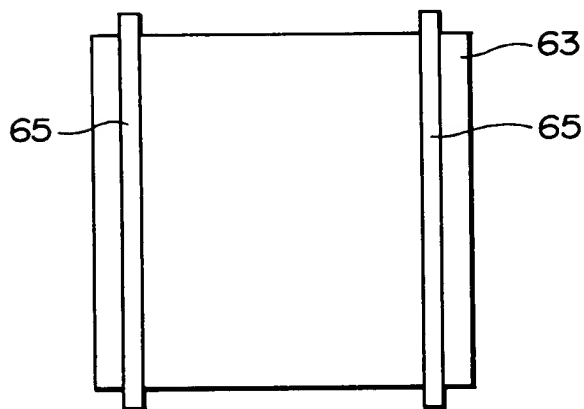


FIG.12B





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FIG.13A

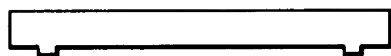


FIG.13C

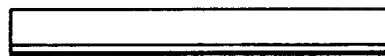


FIG.13B

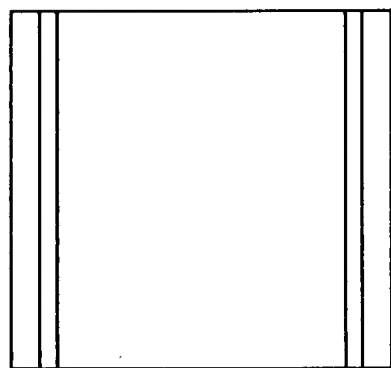


FIG.14A

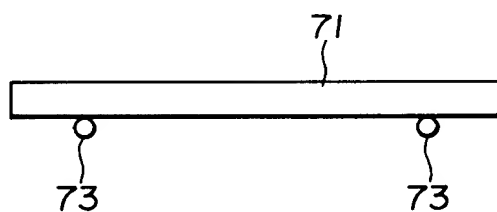


FIG.14B

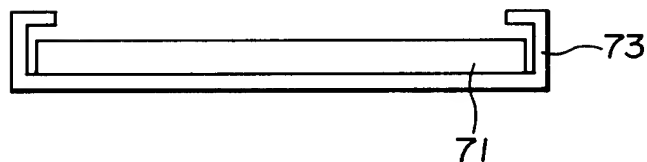




FIG.15A

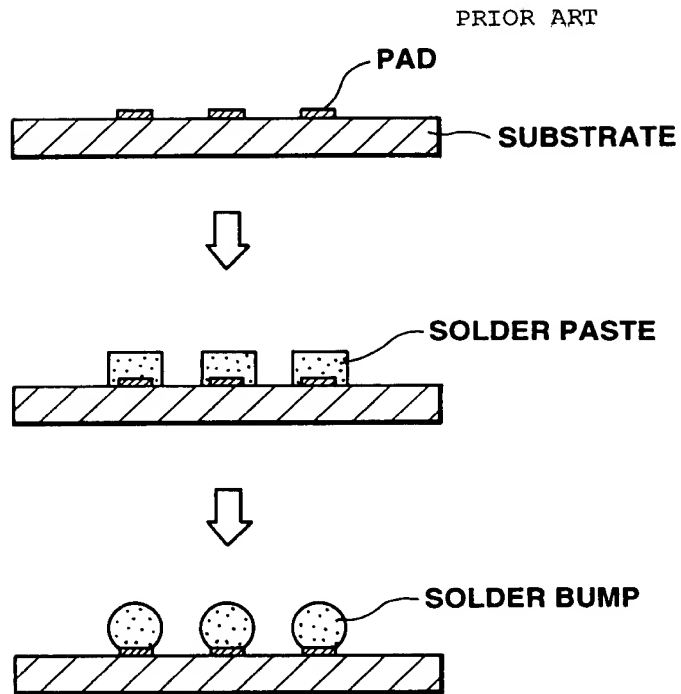


FIG.15B

